

FutureHorizons



The Global Semiconductor Industry Analysts

FH MONDAY

5 July 2021

Radar Chip Targeted at Next-Level ADAS

Improving the “eyes” of driver assistance systems is extending beyond cameras and lidar to include development of new sensors capable of handling complex driving scenarios, or what the auto industry calls Level 4, or “high” automation.

[read more](#)

Mythic Resizes its AI Chip

Mythic, the startup building analog AI chips based on compute-in-memory technology using arrays of Flash transistors, has raised \$70 million and launched a second, slightly smaller chip based on the original architecture.

[read more](#)

Marvell Extends OCTEON Leadership with Industry's First 5nm DPUs

Marvell's OCTEON 10 DPU is the first to be designed on a 5nm process to incorporate Arm Neoverse N2 cores. Marvell has launched the new OCTEON 10 DPU designed to accelerate and process a broad spectrum of security, networking, and storage workloads required by demanding 5G, cloud, carrier and enterprise datacenter applications.

[read more](#)

FutureHorizons



TALK TO US



MaxPower and Renesas to Collaborate on Complete Power Solutions

MaxPower Semiconductor Inc. and Renesas have agreed to work together in order to provide more efficient and complete power solutions to their customers. MaxPower's novel power semiconductor products will be combined with Renesas' broad product offerings to streamline the design process and provide a competitive edge and optimized performance for existing and future customers.

[read more](#)

EVENTS

[Silicon Chip Industry Seminar](#)

-November 2021- London UK

[Industry Forecast Briefing](#)

- September 2021- London UK

**DON'T MISS OUT.-
BOOK NOW BY
CALLING**

+44 1732 740440

OR EMAIL

mail@futurehorizons.com

Qualcomm Enhances Snapdragon Performance

Qualcomm has outlined details of its latest Snapdragon 888 Plus chipset, which now has a 3GHz prime CPU core and a much improved AI engine.

[read more](#)

Future Horizons Ltd, • 44 Bethel Road • Sevenoaks • Kent TN13 3UE • England

Tel: +44 1732 740440 • Fax: +44 1732 740442

e-mail: mail@futurehorizons.com • <http://www.futurehorizons.com/>

Affiliates in Europe, India, Israel, Japan, Russian, San Jose California, USA

Radar Chip Targeted at Next-Level ADAS

Improving the “eyes” of driver assistance systems is extending beyond cameras and lidar to include development of new sensors capable of handling complex driving scenarios, or what the auto industry calls Level 4, or “high” automation.

Among the developers is Vayyar Imaging, the Israeli sensor specialist. It's XRR platform aimed at advanced driver assistance systems (ADAS) is a single 4D imaging radar chip with a range of up to 300 meters. The radar chip also provides a 180-degree field of view, operating without the need for an external processor.

The 4D feature refers to the chip's ability to measure distance and relative velocity along with the azimuth of objects and their height relative to the road level.

Mythic Resizes its AI Chip

Mythic, the startup building analog AI chips based on compute-in-memory technology using arrays of Flash transistors, has raised \$70 million and launched a second, slightly smaller chip based on the original architecture.

The Series C round, led by BlackRock and Hewlett Packard Enterprise, brings Mythic's total funding to \$165.2 million. The company said it would use the funds to accelerate plans for volume production of its analog AI chip products as well as working on next generation hardware while building out its software portfolio.

Marvell Extends OCTEON Leadership with Industry's First 5nm DPUs

Marvell has launched the new OCTEON 10 DPU designed to accelerate and process a broad spectrum of security, networking, and storage workloads required by demanding 5G, cloud, carrier and enterprise datacenter applications.

With the increasing shift of workloads to the cloud, complex security requirements and the growing number of edge devices the demand for data centric compute has accelerated. By combining compute with best-in-class hardware accelerators, Marvell's OCTEON 10 DPU offers a significant TCO advantage and features numerous industry firsts. Delivering three times the performance and 50 percent lower power compared to previous generations of OCTEON, the newly announced solution is the first to be designed on a 5nm process to incorporate Arm Neoverse N2 cores, as well as the first inline artificial intelligence/machine learning (AI/ML) hardware acceleration, the first integrated 1 terabit switch and the first to incorporate vector packet processing (VPP) hardware accelerators.

MaxPower and Renesas to Collaborate on Complete Power Solutions

MaxPower Semiconductor Inc. and Renesas have agreed to work together in order to provide more efficient and complete power solutions to their customers. MaxPower's novel power semiconductor products will be combined with Renesas' broad product offerings to streamline the design process and provide a competitive edge and optimized performance for existing and future customers.

Renesas and MaxPower are collaborating to offer improved efficiency power semiconductor products used in power tools, vacuum cleaners, industrial motor drives and mobility applications. A leading example product is driving a full-size BLDC vacuum motor that will allow for improved performance in traditional cordless upright and canister vacuums.

Qualcomm Enhances Snapdragon Performance

Qualcomm was one of the few companies making important announcements during the first day of this year's (mostly virtual) Mobile World Congress.

Though not actually present, the San Diego-based chip group outlined details of its latest Snapdragon 888 Plus chipset, which now has a 3GHz prime CPU core and a much improved AI engine that Qualcomm says offers a 20% better performance compared to the original Snapdragon 888 launched six months ago.

Several companies, including Motorola, Asus, Vivo and Xiaomi have already said they plan to use the Plus engine in devices to be introduced by the third quarter of the year.

Perhaps more significantly for the long term, Qualcomm said it is winning increased support for 5G mmWave frequencies globally, and introduced what it says is the first 3GPP release 16 small cell platform, the FSM200xx, as well as higher performance 5G Distributed Unit (DU) X100 accelerator cards.

Both should give the 5G ecosystem a major boost and accelerate the shift towards 5G virtual/ Open RAN.